

RF360 Europe GmbH

A Qualcomm – TDK Joint Venture

SAW components

SAW RF filter

Automotive telematics
Bluetooth

Series/type:	B4360
Ordering code:	B39242B4360P810
Date:	December 02, 2016
Version:	2.1

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1 Application

- Low-loss RF filter for bluetooth
- No external matching components required
- Usable pass band 83.5 MHz

2 Features

- Package size 1.1±0.1 mm × 0.9±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- AEC-Q200 qualified component family
(Grade 1: -40 °C to +125 °C)

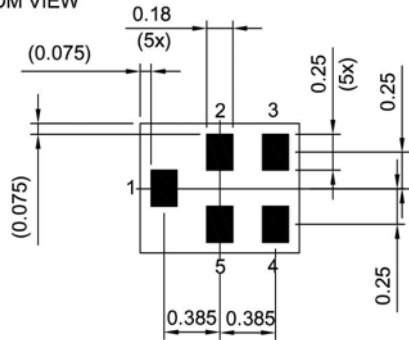


Figure 1: Picture of component with example of product marking.

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3 Package

BOTTOM VIEW



Pad and pitch tolerance ±0.05

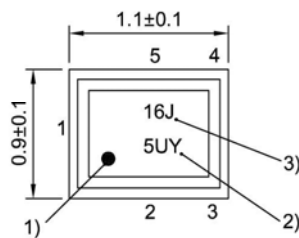
4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW

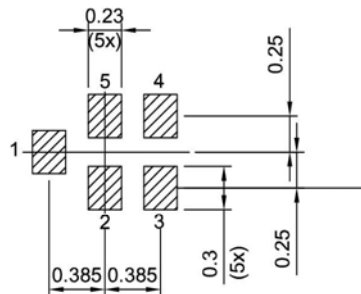


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 17).

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5 Matching circuit

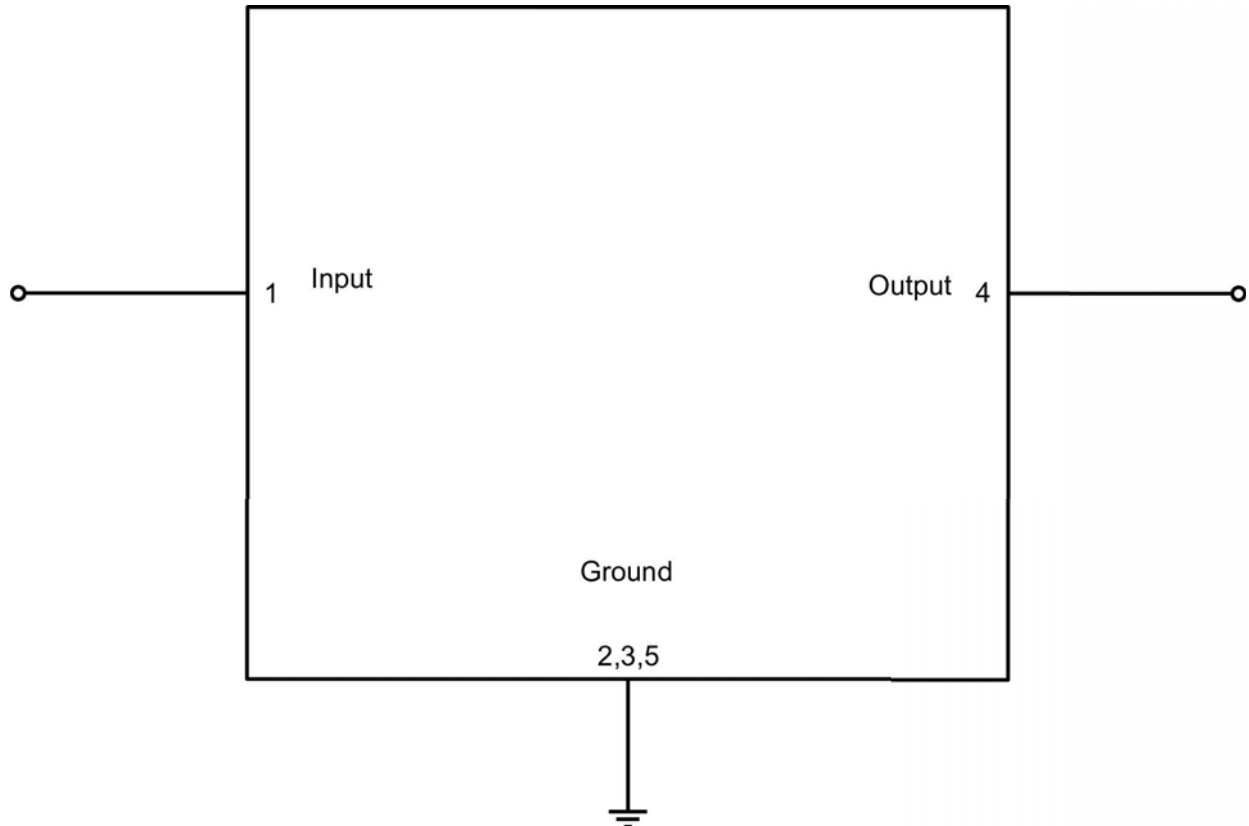


Figure 3: Schematic of matching circuit. No external matching components required.

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6 Characteristics

Temperature range for specification	T_{SPEC}	= -30 °C ... +85 °C
Input terminating impedance	Z_{IN}	= 50 Ω
Output terminating impedance	Z_{OUT}	= 50 Ω

Characteristics		min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency		—	2441.75	—	MHz
Maximum insertion attenuation					
	2400 ... 2483.5 MHz	—	2.1	3.0	dB
Amplitude ripple (p-p)					
	2400 ... 2483.5 MHz	—	0.9	1.8	dB
Maximum VSWR					
@ input port	2400 ... 2483.5 MHz	—	1.8	2.2	
@ output port	2400 ... 2483.5 MHz	—	1.8	2.2	
Minimum attenuation					
	699 ... 787 MHz	24	30	—	dB
	791 ... 960 MHz	22	29	—	dB
	1452 ... 1496 MHz	22	28	—	dB
	1710 ... 2170 MHz	23	28	—	dB
	2570 ... 2620 MHz	24	36	—	dB
	2620 ... 2690 MHz	24	33	—	dB
	3400 ... 3800 MHz	24	31	—	dB

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7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +125\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +125\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
Input power @ input port: 2400 ... 2483,5 MHz	$P_{IN} = 20\text{ dBm}$	Continuous wave for 5000 h @ 55 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

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8 Transmission coefficient

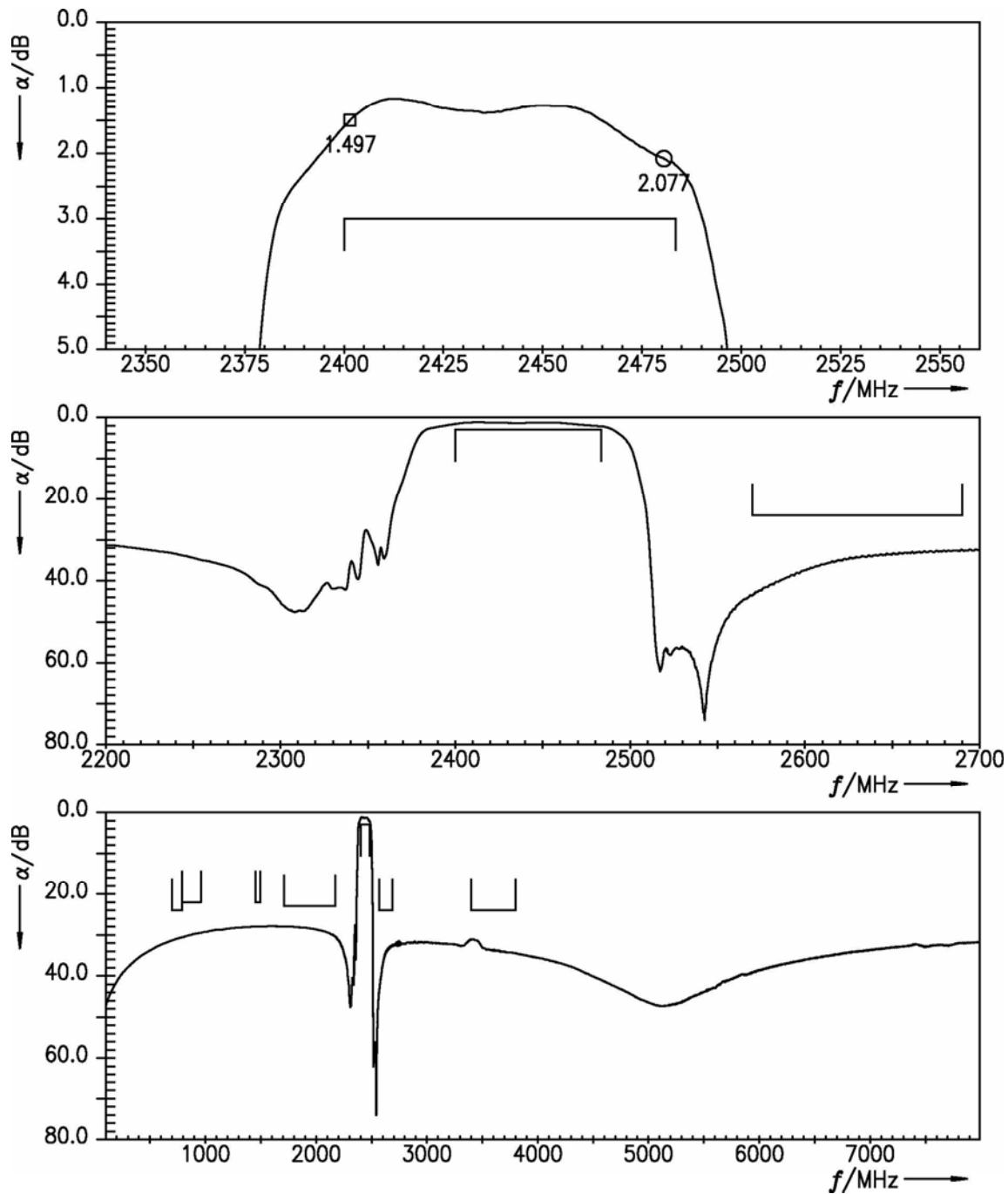


Figure 4: Attenuation.

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9 Reflection coefficients

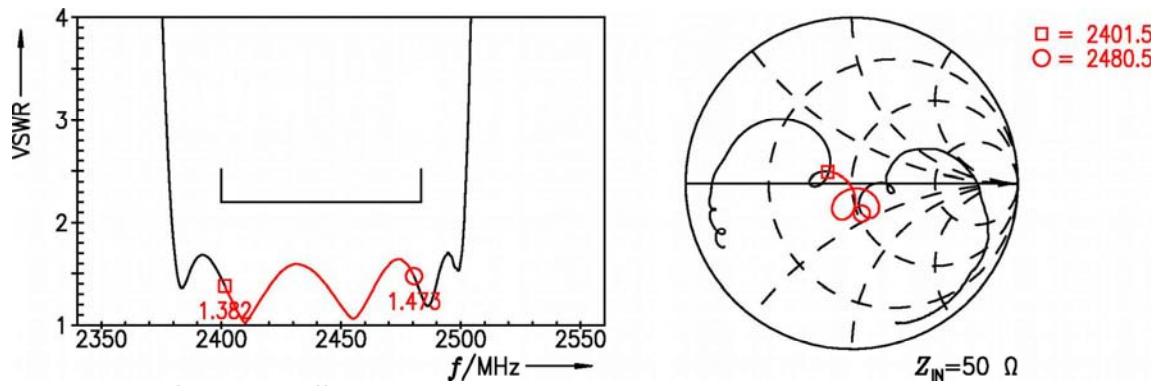


Figure 5: Reflection coefficient at IN port.

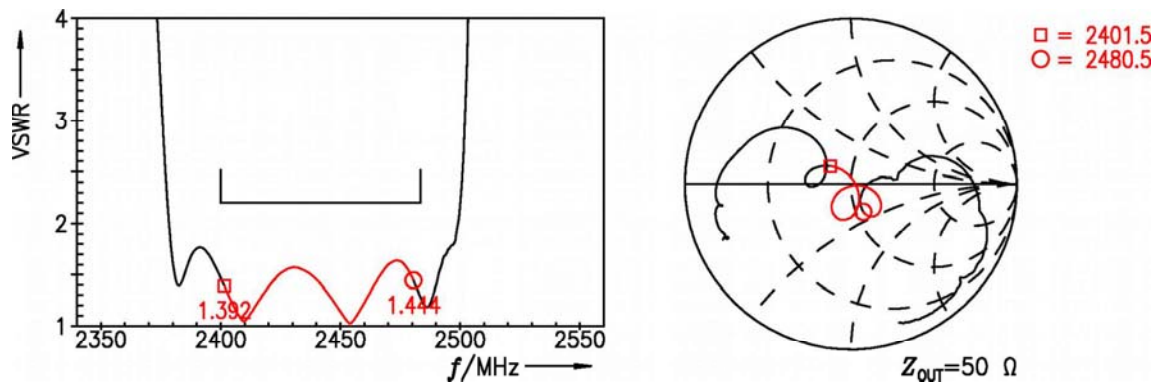
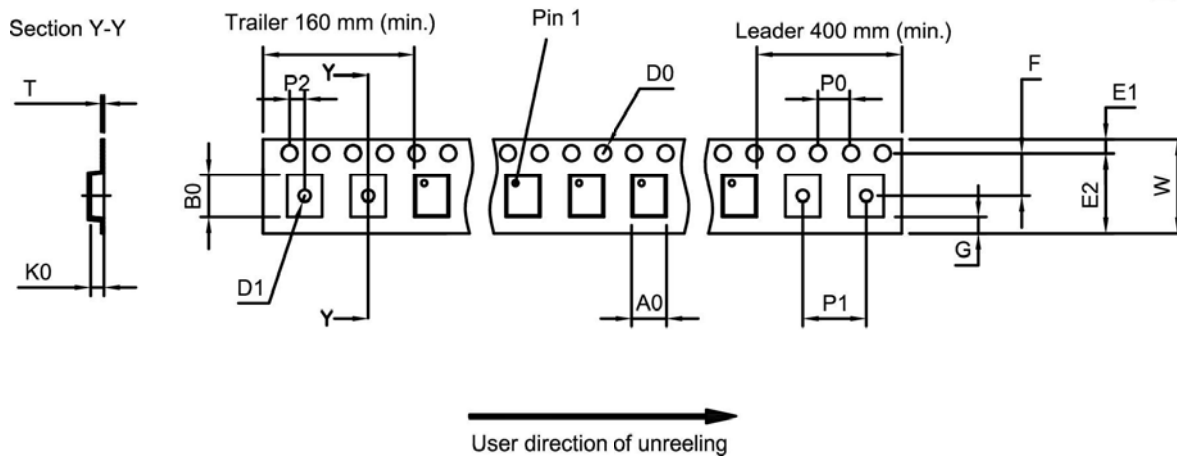


Figure 6: Reflection coefficient at OUT port.

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10 Packing material
10.1 Tape

Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	1.02 ± 0.05 mm	E_2	6.25 mm (min.)	P_1	2.0 ± 0.1 mm
B_0	1.22 ± 0.05 mm	F	3.5 ± 0.05 mm	P_2	2.0 ± 0.05 mm
D_0	1.55 ± 0.05 mm	G	–	T	0.25 ± 0.03 mm
D_1	0.55 ± 0.1 mm	K_0	0.6 ± 0.05 mm	W	$8.0 + 0.3 / - 0.1$ mm
E_1	1.75 ± 0.1 mm	P_0	4.0 ± 0.1 mm		

Table 1: Tape dimensions.

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10.2 Reel with diameter of 180 mm

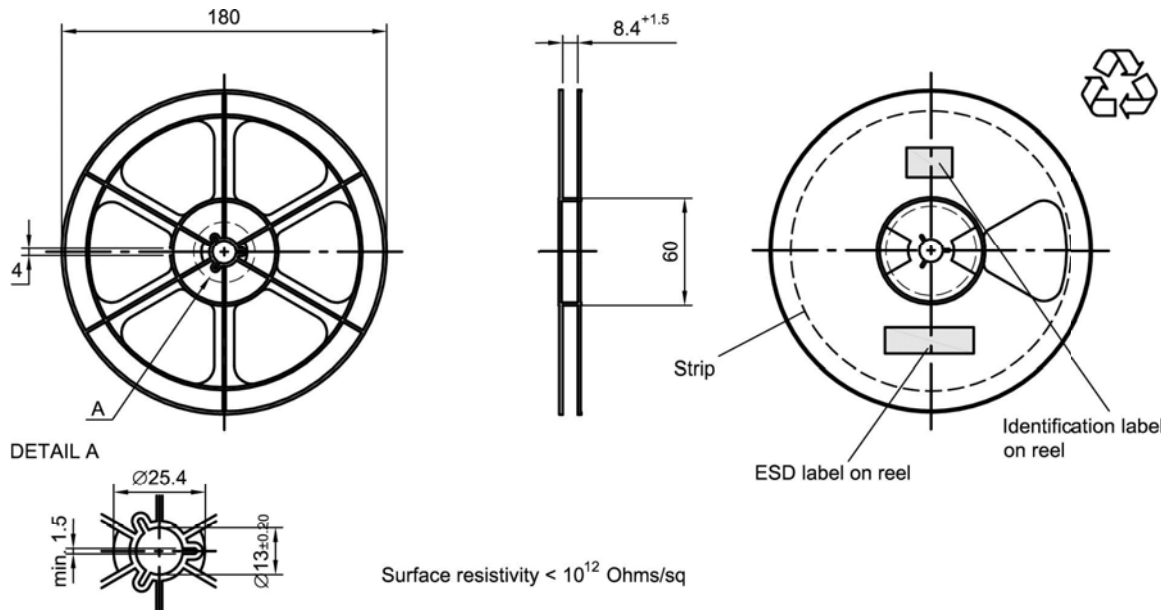


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]
 X = 220+5
 Y = 235+5
 Sealing area 10±3

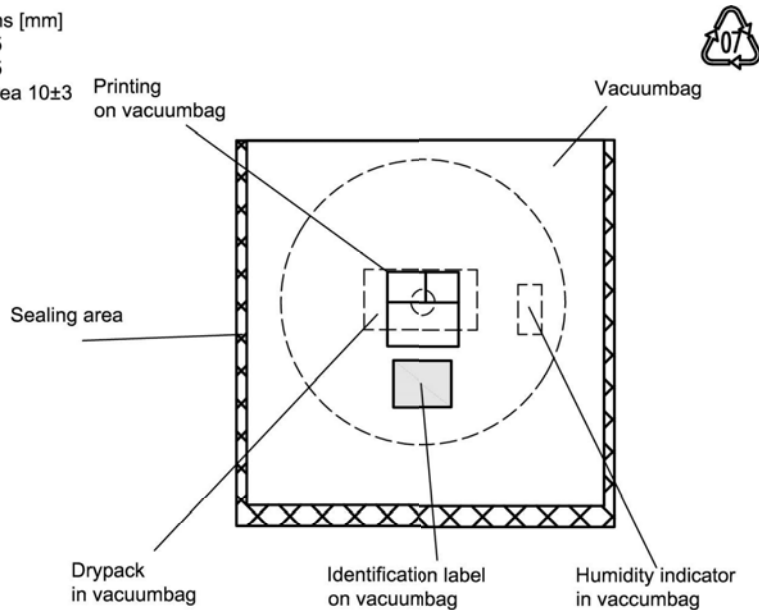


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

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Dimensions [mm]

L = 188

B = 188

H = 30

Tolerance ± 5

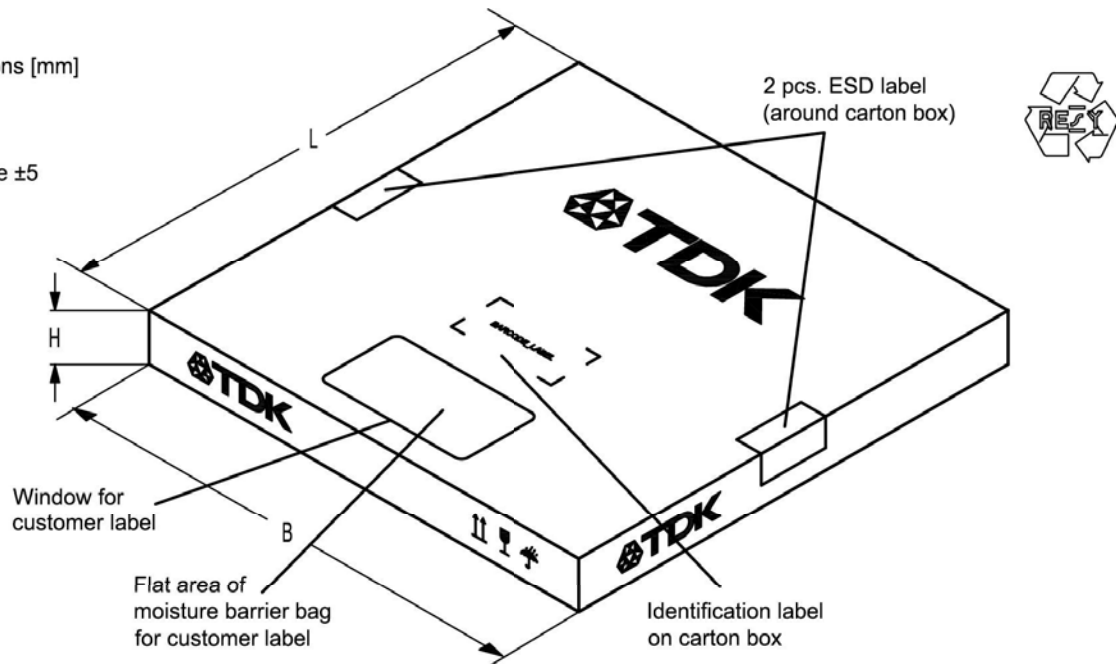


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

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11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

 The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx, is encoded by a special BASE32 code into a 3 digit marking.

 Example of decoding type number marking on device in decimal code.

$$\begin{array}{rcl}
 \mathbf{16J} & \Rightarrow & \mathbf{1234} \\
 \mathbf{1} \times 32^2 + \mathbf{6} \times 32^1 + \mathbf{18 (=J)} \times 32^0 & = & \mathbf{1234}
 \end{array}$$

The BASE32 code for product type B4360 is 488.

■ Lot number:

 The last 5 digits of the lot number, e.g., **12345**, are encoded based on a special BASE47 code into a 3 digit marking.

 Example of decoding lot number marking on device in decimal code.

$$\begin{array}{rcl}
 \mathbf{5UY} & \Rightarrow & \mathbf{12345} \\
 \mathbf{5} \times 47^2 + \mathbf{27 (=U)} \times 47^1 + \mathbf{31 (=Y)} \times 47^0 & = & \mathbf{12345}
 \end{array}$$

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

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12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

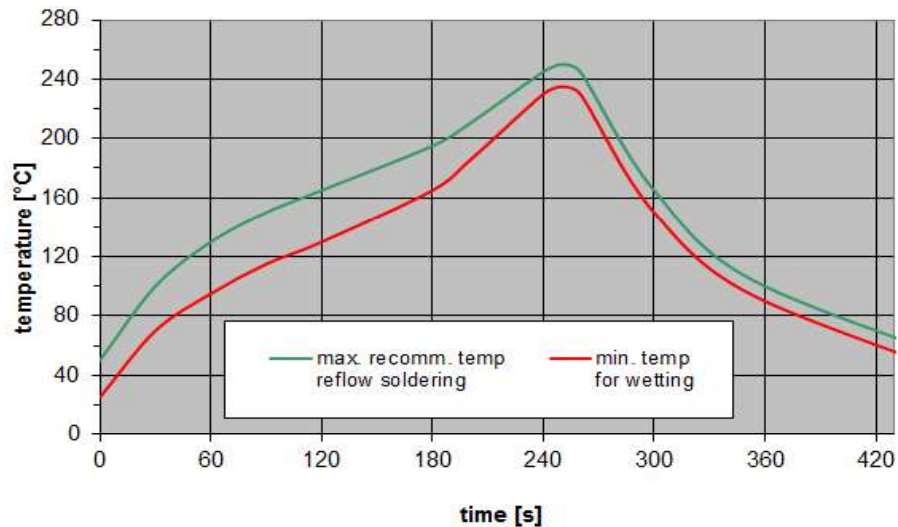


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

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13 ESD protection of SAW filters

SAW filters are **Electro Static Discharge** sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

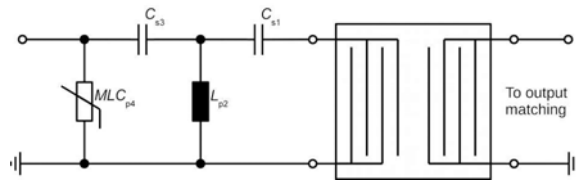


Figure 12: MLC varistor plus ESD matching.

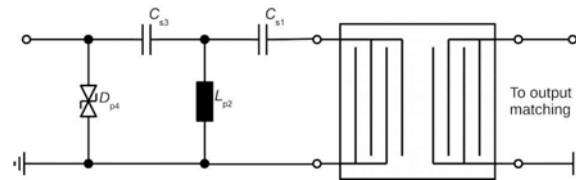


Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

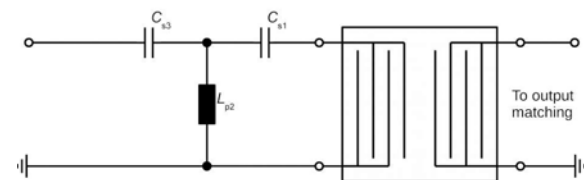


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to EPCOS Application report: “**ESD protection for SAW filters**”. This report can be found under www.epcos.com/rke. Click on “Applications Notes”.

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14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

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15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

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15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

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